## (19) INDIA

(22) Date of filing of Application :18/09/2024

(43) Publication Date : 04/10/2024

(51) International classification (86) International Application No Filing Date (87) International Publication No (61) Patent of Addition to Application Number Filing Date (62) Divisional to Application Number Filing Date	:H01L0029872000, H01L0029660000, H01L0029510000, H01L0021285000, H01L0029200000 :NA :NA :NA :NA :NA :NA	<ul> <li>(71)Name of Applicant :</li> <li>1)Malla Reddy Engineering College         Address of Applicant :Dhulapally post via Kompally Maisammaguda Secunderabad -500100 Secunderabad         The ansana Lakshmi         Name of Applicant : NA         (72)Name of Inventor:         1)Dr. B. Prasana Lakshmi         Address of Applicant : NA         (72)Name of Inventor:         1)Dr. B. Prasana Lakshmi         Address of Applicant :Associate Professor Department ofPhysics, Malla Reddy Engineering College,         Maisammaguda (Post. Via. Kompally).Medchal-Malkajgiri-500100. State:Telangana Email ID:         drpraannalakshmi85@gmail.com Number:630380002 Secunderabad         2)Mr. Kesava Vansi Krishna Vajjlal         Address of Applicant :Associate Professor Department of Physics, Malla Reddy Engineering College,         Maisammaguda (Post. Via. Kompally).Medchal-Malkajgiri-500100. State:Telangana Email ID:         mreephysics@gmail.com Number:63032 34705 Secunderabad        </li></ul>
		State:Telangana Email ID: nithyarameshphd1981@gmail.com Number:95663 82542 Secunderabad

(57) Abstract

(57) Abstract : Gallium nitride (GaN) has been considered as a superior materialfor applications in high-power and high-frequency transistorsoperating at elevated temperatures, owing to their large anddirect band gap, as well as favorable transport properties. There has been considerable interest in the experimentalstudies of metal-semiconductor (MS), metal-insulator-semiconductor(MIS) type Schottky diodes in the past decades. The popularity of such studies, rooted in their importance to the insulator layer between metal and semiconductor. The existence of such interfacial insulator layer converts the MSdiodes to MIS type diodes and can have strong influence on thedevice characteristics as well as the interface state density (NSS), Schottky barrier height (BH) and ideality factor (n). We have investigated the current-voltage (I-V) characteristics of (Au/SiO2/n-GaN) metal-insulator-semiconductor (MIS) Schottky diodes and compared with (Au/n-GaN) metal-semiconductor (MS) Schottky diode. The effect of SiO2 on the surface preparation of n-GaN (MIS) Schottky diode is analyzed. It is observed that the Schottky barrier height increases from 0.79eV to 0.86 eV, the ideality factor deceases from 1.45 to 1.3, by inserting the SiO2 insulating layer. The interface state density as determined by Terman's method is found to be 3.79×1012and 3.41×1010 cm-2 eV-1 for the MS and MIS Schottky diodes, which again decreased by the insulating layer.

No. of Pages : 5 No. of Claims : 5